

MECHANICAL CASE OUTLINE

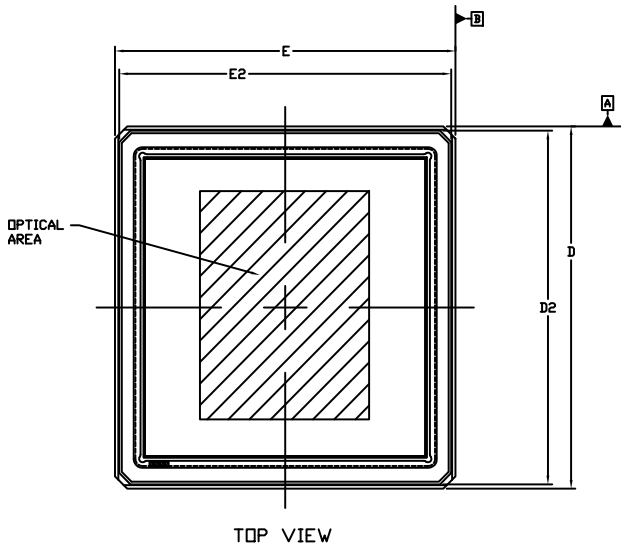
PACKAGE DIMENSIONS

ON Semiconductor®



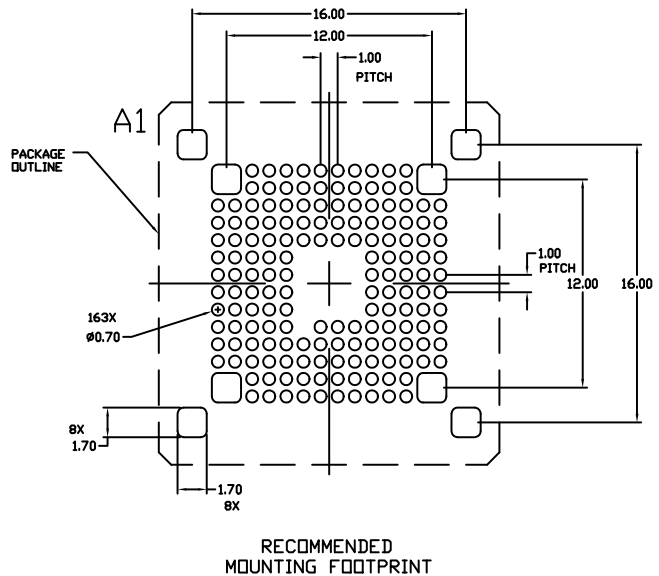
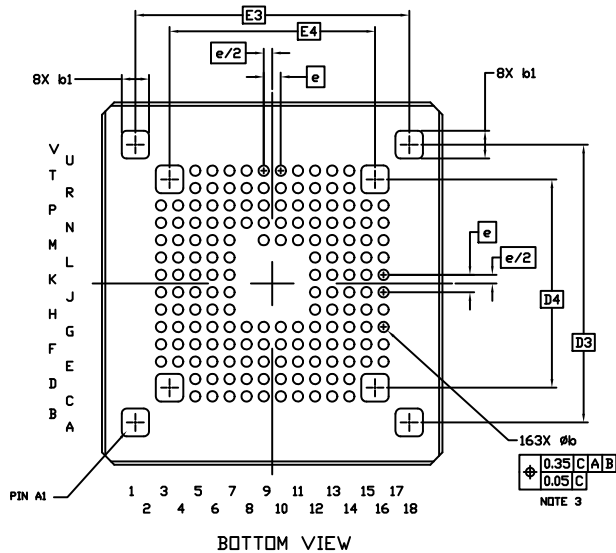
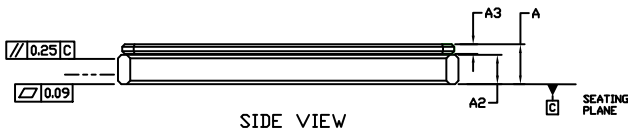
CLGA163 20.88x19.9, 1P CASE 621AB ISSUE 0

DATE 06 APR 2018



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS
 3. POSITIONAL TOLERANCE APPLIES TO ALL PADS.

DIM	MILLIMETERS	
	MIN.	MAX.
A	---	2.54
A2	1.53	1.87
A3	0.55 REF	
b	0.55	0.65
b1	1.60 REF	
D	20.76	21.00
D2	20.30	20.46
D3	16.00 BSC	
D4	12.00 BSC	
E	19.80	20.00
E2	19.32	19.48
E3	16.00 BSC	
E4	12.00 BSC	
e	1.00 BSC	



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